# XP0111F (XP111F)

### Silicon PNP epitaxial planer transistor

#### For switching/digital circuits

#### Features

- Two elements incorporated into one package. (Emitter-coupled transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half.

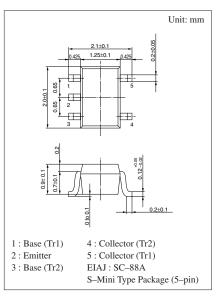
#### Basic Part Number of Element

• UNR111F(UN111F)  $\times$  2 elements

Parameter		Symbol	Ratings	Unit
Rating of element	Collector to base voltage	V <sub>CBO</sub>	-50	V
	Collector to emitter voltage	V <sub>CEO</sub>	-50	V
	Collector current	I <sub>C</sub>	-100	mA
Overall	Total power dissipation	P <sub>T</sub>	150	mW
	Junction temperature	Tj	150	°C
	Storage temperature	T <sub>stg</sub>	-55 to +150	°C

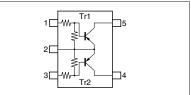
#### Absolute Maximum Ratings (Ta=25°C)

Electrical Characteristics (Ta=25°C)



#### Marking Symbol: 70

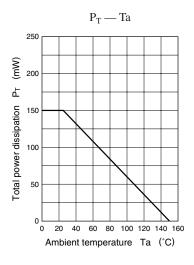
#### Internal Connection

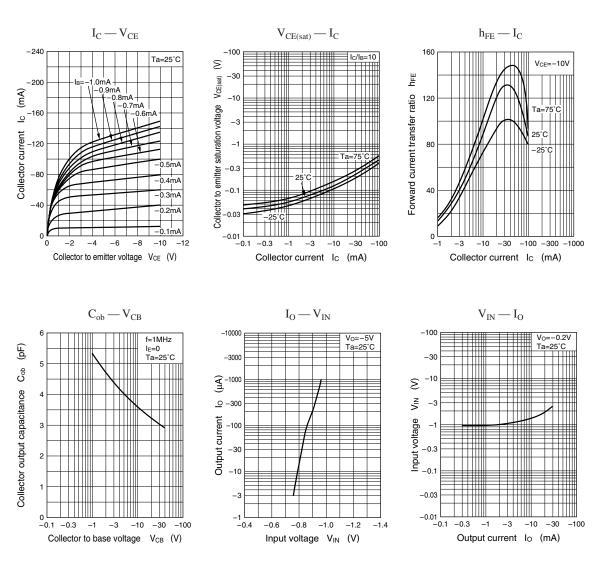


#### Conditions Parameter Symbol min max Unit typ $I_{\rm C} = -10\mu A, I_{\rm E} = 0$ V Collector to base voltage V<sub>CBO</sub> -50V Collector to emitter voltage V<sub>CEO</sub> $I_{C} = -2mA, I_{B} = 0$ -50 $V_{CB} = -50V, I_E = 0$ -0.1μΑ $I_{CBO}$ Collector cutoff current $V_{CE} = -50V, I_B = 0$ -0.5μΑ I<sub>CEO</sub> $V_{EB} = -6V, I_C = 0$ Emitter cutoff current I<sub>EBO</sub> -1.0mA Forward current transfer ratio $V_{CE} = -10V, I_C = -5mA$ 30 h<sub>FE</sub> hFE (small/large)\*1 $V_{CE} = -10V, I_C = -5mA$ 0.5 0.99 Forward current transfer $h_{\text{FE}}$ ratio Collector to emitter saturation voltage V<sub>CE(sat)</sub> $I_{C} = -10mA$ , $I_{B} = -0.3mA$ -0.25V $V_{CC} = -5V, V_B = -0.5V, R_L = 1k\Omega$ V Output voltage high level VOH -4.9 $V_{CC} = -5V, V_B = -2.5V, R_L = 1k\Omega$ V Output voltage low level VOL -0.2 $V_{CB} = -10V, I_E = 1mA, f = 200MHz$ MHz Transition frequency $f_{T} \\$ 80 Input resistance -30% +30% $R_1$ 4.7 kΩ Resistance ratio $R_1/R_2$ 0.47

\*1 Ratio between 2 elements

Note.) The Part number in the Parenthesis shows conventional part number.





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